



# PSMN1R5-60YSN

N-channel 60 V, 1.5 mOhm, standard level NextPowerS3  
MOSFET in LFPAK56E

25 April 2024

Objective data sheet

## 1. General description

NextPowerS3 family leverages “superjunction” and Schottky-Plus technologies for super-fast switching with soft body-diode recovery, delivering low spiking without compromising efficiency or  $I_{DSS}$  leakage. This product has been designed and qualified for high performance power switching applications.

## 2. Features and benefits

- 250 A continuous  $I_{D(max)}$
- Avalanche rated, 100% tested
- High reliability LFPAK (Power SO8) package, qualified to 175 °C
- LFPAK copper clip:
  - Improved thermal dissipation and even current distribution
  - Reduced electrical and thermal resistance
- LFPAK gull wing lead:
  - Enhanced wetting area for solder coverage and visual soldering inspection
  - High Board Level Reliability, absorbing thermal expansion and mechanical strain

## 3. Applications

- eFuse
- Battery protection
- Motor control
- Power supply for servers and telecoms
- DC-to-DC converters

## 4. Quick reference data

Table 1. Quick reference data

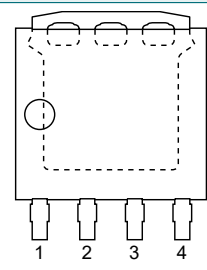
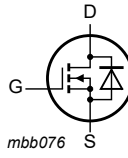
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{DS}$	drain-source voltage	$25\text{ °C} \leq T_j \leq 175\text{ °C}$	-	-	60	V
$I_D$	drain current	$V_{GS} = 10\text{ V}; T_{mb} = 25\text{ °C}$	-	-	250	A
$P_{tot}$	total power dissipation	$T_{mb} = 25\text{ °C}; \text{Fig. 1}$	-	-	250	W
$T_j$	junction temperature		-55	-	175	°C
<b>Static characteristics</b>						
$R_{DSon}$	drain-source on-state resistance	$V_{GS} = 10\text{ V}; I_D = 25\text{ A}; T_j = 25\text{ °C}$	[tbd]	1.2	1.5	mΩ
<b>Dynamic characteristics</b>						
$Q_{GD}$	gate-drain charge	$I_D = 25\text{ A}; V_{DS} = 30\text{ V}; V_{GS} = 10\text{ V}; T_j = 25\text{ °C}$	[tbd]	79	[tbd]	nC
$Q_{G(tot)}$	total gate charge		[tbd]	236	[tbd]	nC

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Avalanche ruggedness</b>						
$E_{DS(AL)S}$	non-repetitive drain-source avalanche energy	$V_{sup} \leq 60\text{ V}$ ; $V_{GS} = 10\text{ V}$ ; $T_{j(\text{init})} = 25\text{ }^\circ\text{C}$ ; unclamped	[1]	-	-	[tbd] mJ
<b>Source-drain diode</b>						
$Q_r$	recovered charge	$I_S = 25\text{ A}$ ; $di_S/dt = -100\text{ A}/\mu\text{s}$ ; $V_{GS} = 0\text{ V}$ ; $V_{DS} = 30\text{ V}$ ; $T_j = 25\text{ }^\circ\text{C}$ ; Fig. 2	[2]	-	[tbd]	- nC

- [1] Protected by 100% test.
- [2] includes capacitive recovery

## 5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	S	source	 <p>LPAK56E; Power-SO8 (SOT1023)</p>	 <p>mbb076</p>
2	S	source		
3	S	source		
4	G	gate		
mb	D	mounting base; connected to drain		

## 6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PSMN1R5-60YSN	LPAK56E; Power-SO8	plastic, single-ended surface-mounted package (LPAK56E); 4 leads; 1.27 mm pitch	SOT1023

## 7. Limiting values

Table 4. Limiting values

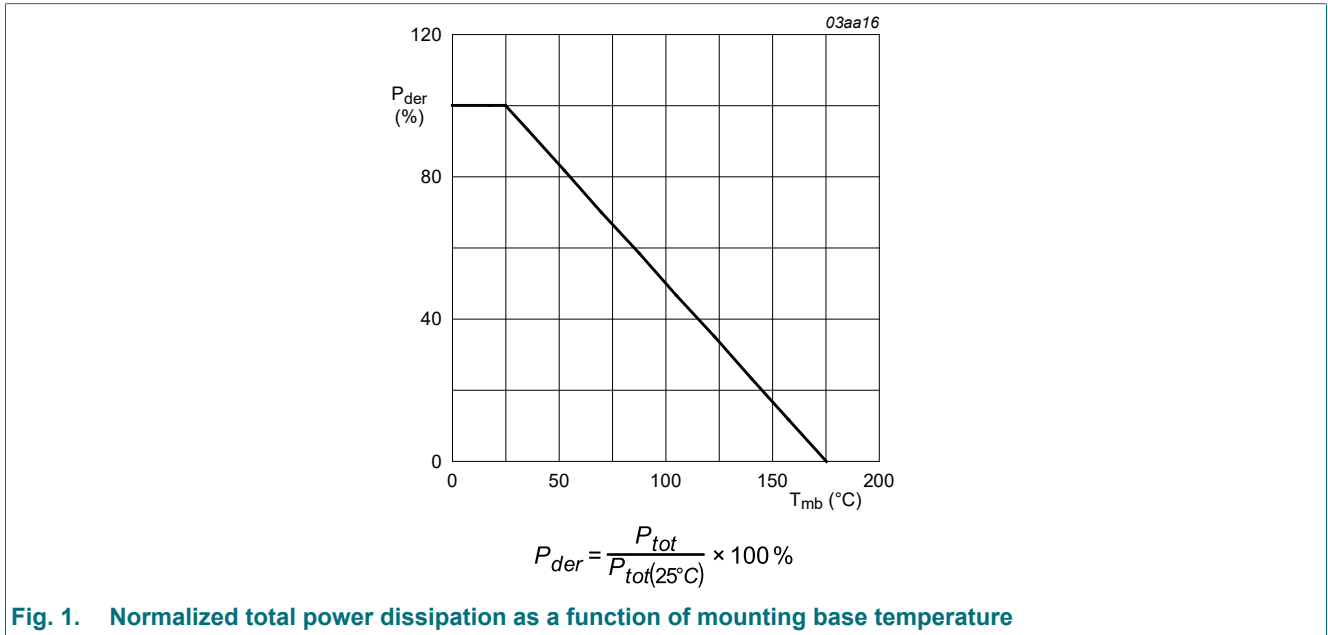
In accordance with the Absolute Maximum Rating System (IEC 60134).  $T_j = 25\text{ }^\circ\text{C}$  unless otherwise stated.

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{DS}$	drain-source voltage	$25\text{ }^\circ\text{C} \leq T_j \leq 175\text{ }^\circ\text{C}$	-	60	V
$V_{GS}$	gate-source voltage		-20	20	V
$P_{tot}$	total power dissipation	$T_{mb} = 25\text{ }^\circ\text{C}$ ; Fig. 1	-	250	W
$I_D$	drain current	$V_{GS} = 10\text{ V}$ ; $T_{mb} = 25\text{ }^\circ\text{C}$	-	250	A
$I_{DM}$	peak drain current	pulsed; $t_p \leq 10\text{ }\mu\text{s}$ ; $T_{mb} = 25\text{ }^\circ\text{C}$	-	1152	A
$T_{stg}$	storage temperature		-55	175	$^\circ\text{C}$
$T_j$	junction temperature		-55	175	$^\circ\text{C}$
<b>Source-drain diode</b>					
$I_S$	source current	$T_{mb} = 25\text{ }^\circ\text{C}$	-	250	A

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Symbol	Parameter	Conditions		Min	Max	Unit
$I_{SM}$	peak source current	pulsed; $t_p \leq 10 \mu s$ ; $T_{mb} = 25 \text{ }^\circ\text{C}$		-	1152	A
<b>Avalanche ruggedness</b>						
$E_{DS(AL)S}$	non-repetitive drain-source avalanche energy	$V_{sup} \leq 60 \text{ V}$ ; $V_{GS} = 10 \text{ V}$ ; $T_{j(\text{init})} = 25 \text{ }^\circ\text{C}$ ; unclamped	[1]	-	[tbd]	mJ
$I_{AS}$	non-repetitive avalanche current	$T_{j(\text{init})} = 25 \text{ }^\circ\text{C}$	[1]	-	[tbd]	A

[1] Protected by 100% test.



## 8. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base		-	[tbd]	0.6	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient		-	[tbd]	-	K/W

## 9. Characteristics

Table 6. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Static characteristics</b>						
$V_{(BR)DSS}$	drain-source breakdown voltage	$I_D = 250 \mu A$ ; $V_{GS} = 0 \text{ V}$ ; $T_j = 25 \text{ }^\circ\text{C}$	60	[tbd]	-	V
		$I_D = 250 \mu A$ ; $V_{GS} = 0 \text{ V}$ ; $T_j = -55 \text{ }^\circ\text{C}$	-	[tbd]	-	V
$V_{GS(th)}$	gate-source threshold voltage	$I_D = 1 \text{ mA}$ ; $V_{DS}=V_{GS}$ ; $T_j = 25 \text{ }^\circ\text{C}$	2.4	3	3.6	V
		$I_D = 1 \text{ mA}$ ; $V_{DS}=V_{GS}$ ; $T_j = -55 \text{ }^\circ\text{C}$	-	[tbd]	-	V
$\Delta V_{GS(th)}/\Delta T$	gate-source threshold voltage variation with temperature	$25 \text{ }^\circ\text{C} \leq T_j \leq 175 \text{ }^\circ\text{C}$	-	[tbd]	-	mV/K

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Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$I_{DSS}$	drain leakage current	$V_{DS} = 60\text{ V}; V_{GS} = 0\text{ V}; T_j = 25\text{ }^\circ\text{C}$	-	[tbd]	1	$\mu\text{A}$
$I_{GSS}$	gate leakage current	$V_{GS} = 20\text{ V}; V_{DS} = 0\text{ V}; T_j = 25\text{ }^\circ\text{C}$	-	2	100	nA
		$V_{GS} = -20\text{ V}; V_{DS} = 0\text{ V}; T_j = 25\text{ }^\circ\text{C}$	-	2	100	nA
$R_{DS(on)}$	drain-source on-state resistance	$V_{GS} = 10\text{ V}; I_D = 25\text{ A}; T_j = 25\text{ }^\circ\text{C}$	[tbd]	1.2	1.5	m $\Omega$
		$V_{GS} = 10\text{ V}; I_D = 25\text{ A}; T_j = 175\text{ }^\circ\text{C}$	[tbd]	2.4	3.02	m $\Omega$
$R_G$	gate resistance	$f = 1\text{ MHz}; T_j = 25\text{ }^\circ\text{C}$	[tbd]	[tbd]	[tbd]	$\Omega$
<b>Dynamic characteristics</b>						
$Q_{G(tot)}$	total gate charge	$I_D = 25\text{ A}; V_{DS} = 30\text{ V}; V_{GS} = 10\text{ V}; T_j = 25\text{ }^\circ\text{C}$	[tbd]	236	[tbd]	nC
		$I_D = 0\text{ A}; V_{DS} = 0\text{ V}; T_j = 25\text{ }^\circ\text{C}$	-	[tbd]	-	nC
$Q_{GS}$	gate-source charge	$I_D = 25\text{ A}; V_{DS} = 30\text{ V}; V_{GS} = 10\text{ V}; T_j = 25\text{ }^\circ\text{C}$	[tbd]	33	[tbd]	nC
$Q_{GS(th)}$	pre-threshold gate-source charge	$T_j = 25\text{ }^\circ\text{C}$	[tbd]	[tbd]	[tbd]	nC
$Q_{GS(th-pl)}$	post-threshold gate-source charge		[tbd]	[tbd]	[tbd]	nC
$Q_{GD}$	gate-drain charge		[tbd]	79	[tbd]	nC
$V_{GS(pl)}$	gate-source plateau voltage	$I_D = 25\text{ A}; V_{DS} = 30\text{ V}; T_j = 25\text{ }^\circ\text{C}$	-	[tbd]	-	V
$C_{iss}$	input capacitance	$V_{DS} = 30\text{ V}; V_{GS} = 0\text{ V}; f = 1\text{ MHz}; T_j = 25\text{ }^\circ\text{C}$	[tbd]	[tbd]	[tbd]	pF
$C_{oss}$	output capacitance		[tbd]	[tbd]	[tbd]	pF
$C_{rss}$	reverse transfer capacitance		[tbd]	[tbd]	[tbd]	pF
$t_{d(on)}$	turn-on delay time	$V_{DS} = 30\text{ V}; R_L = 1.2\text{ }\Omega; V_{GS} = 10\text{ V}; R_{G(ext)} = 5\text{ }\Omega; T_j = 25\text{ }^\circ\text{C}$	-	[tbd]	-	ns
$t_r$	rise time		-	[tbd]	-	ns
$t_{d(off)}$	turn-off delay time		-	[tbd]	-	ns
$t_f$	fall time		-	[tbd]	-	ns
<b>Source-drain diode</b>						
$V_{SD}$	source-drain voltage	$I_S = 25\text{ A}; V_{GS} = 0\text{ V}; T_j = 25\text{ }^\circ\text{C}$	-	[tbd]	1	V
$t_{rr}$	reverse recovery time	$I_S = 25\text{ A}; di_S/dt = -100\text{ A}/\mu\text{s}; V_{GS} = 0\text{ V};$	-	[tbd]	-	ns
$Q_r$	recovered charge	$V_{DS} = 30\text{ V}; T_j = 25\text{ }^\circ\text{C};$ <a href="#">Fig. 2</a>	[1]	[tbd]	-	nC

[1] includes capacitive recovery

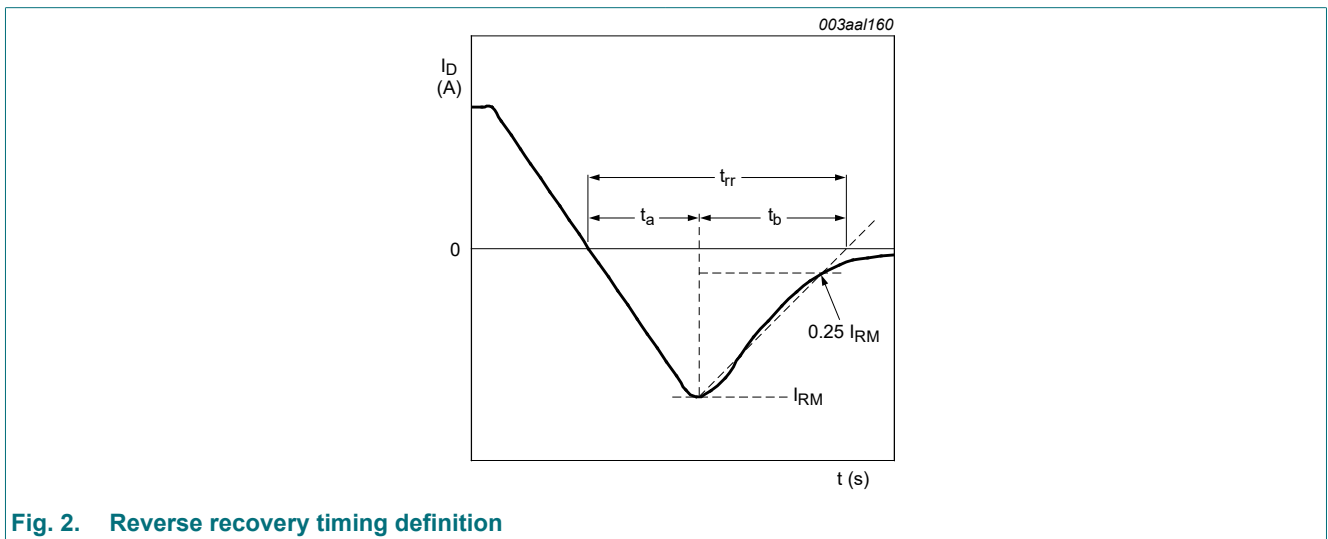


Fig. 2. Reverse recovery timing definition

### 10. Package outline

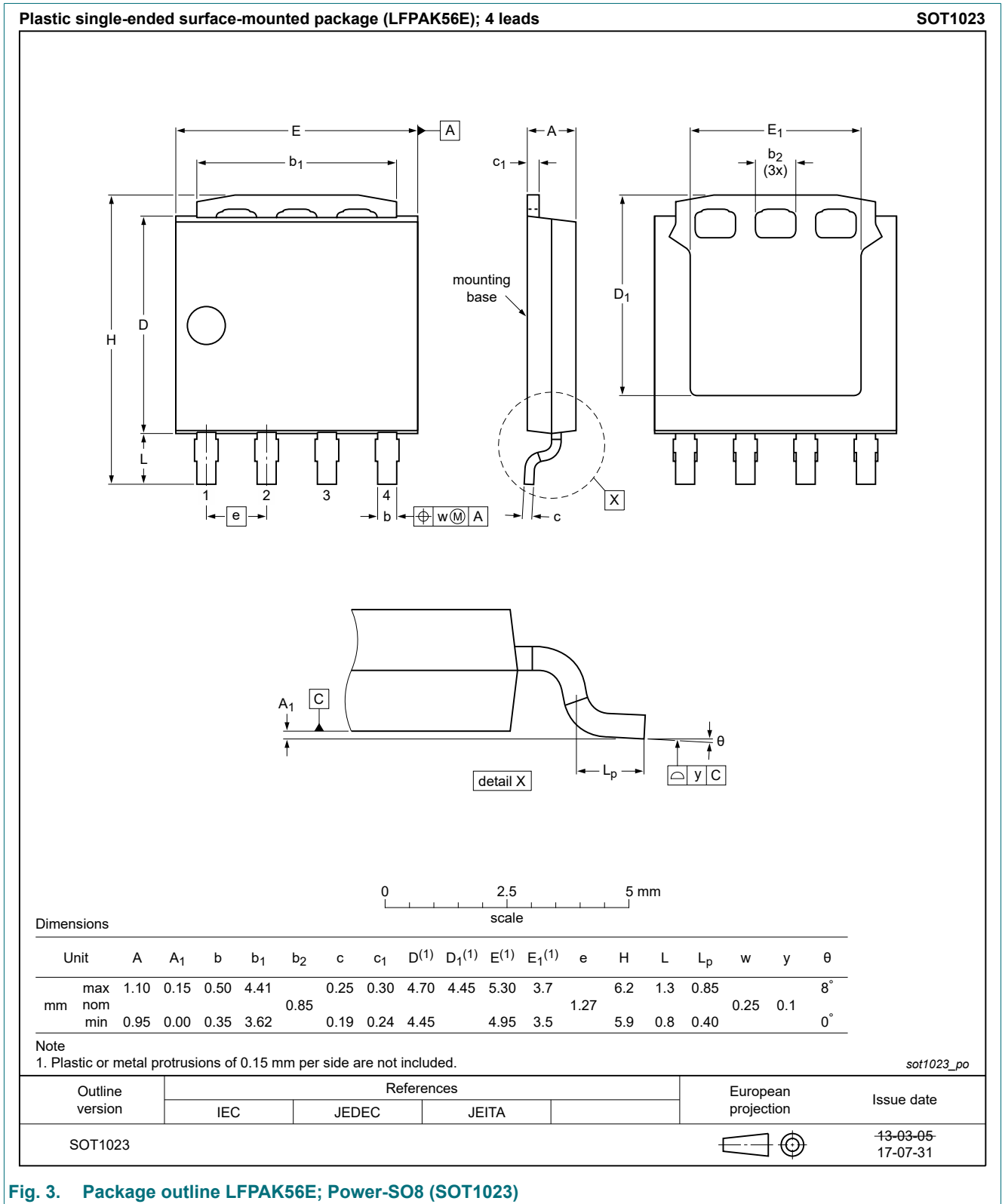


Fig. 3. Package outline LPAK56E; Power-SO8 (SOT1023)

### 11. Soldering

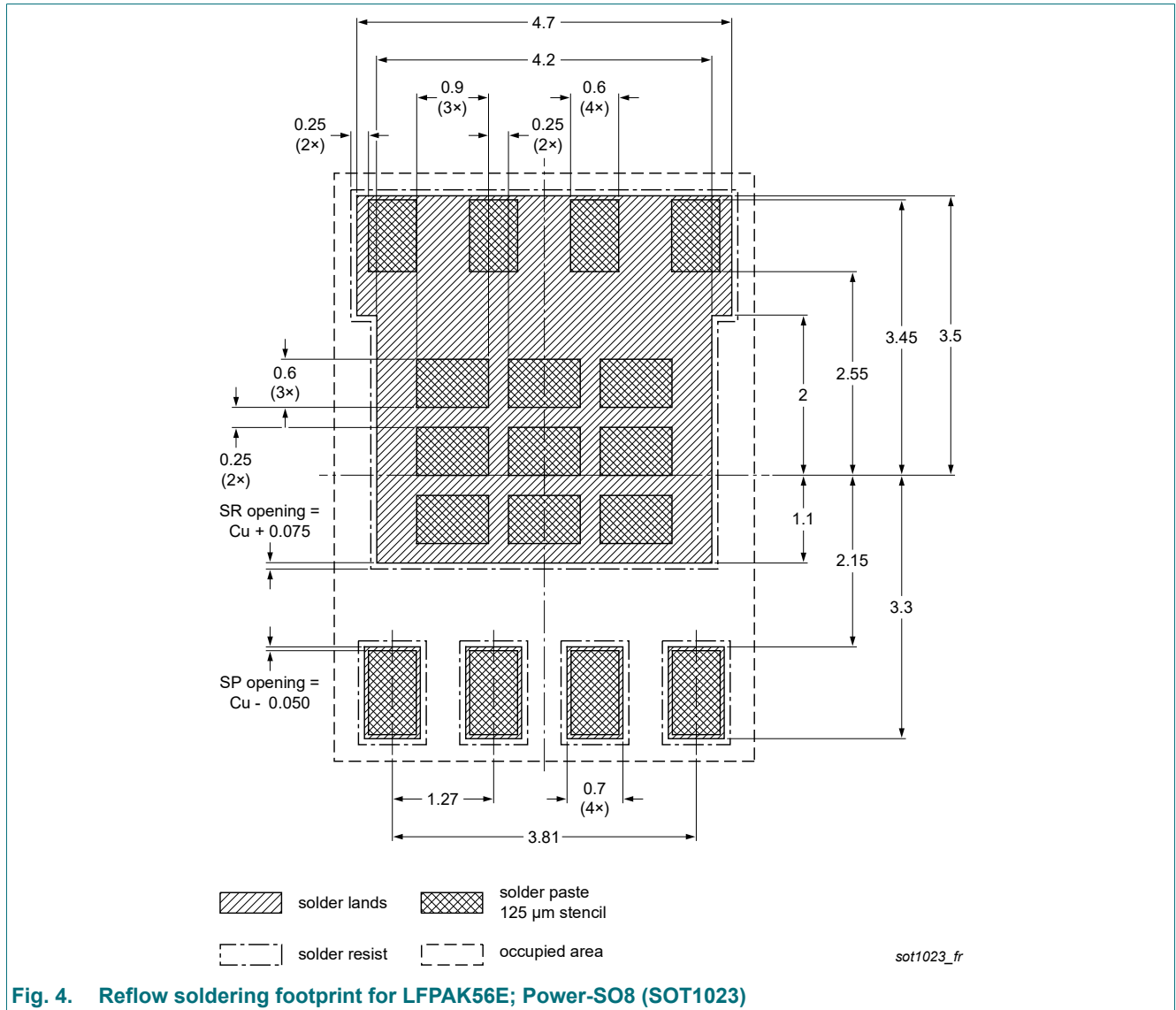


Fig. 4. Reflow soldering footprint for LPAK56E; Power-SO8 (SOT1023)

## 12. Legal information

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Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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